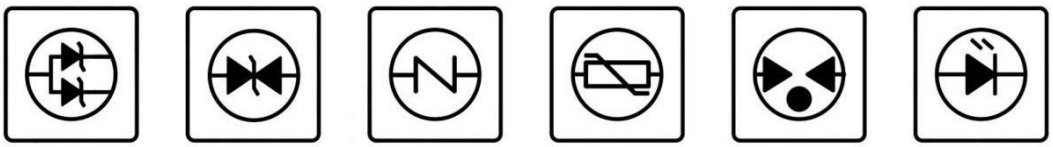
MSKSEMI 美森科
SEMICONDUCTOR



B16WS

Product specification

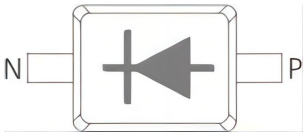
FEATURES

- Guard ring protection.
- Low forward voltage drop.
- For use in low voltage, high frequency inverters .
- High surge current capability.

APPLICATIONS

- Low voltage rectification
- Reverse polarity protection
- Low power consumption applications

Reference News

PACKAGE OUTLINE	Circuit	Marking
 SOD-323		

MAXIMUM RATING (Ta=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
VRRM	Maximum Recurrent Peak Reverse Voltage	60	V
VRMS	Maximum RMS Voltage	42	V
VDC	Maximum DC Blocking Voltage	60	V
IF	Continuous ForwardCurrent	1	A
IFSM	Non-repetitive Peak Forward Surge Current@8.3mS	10	A
Ptot	Total Power Dissipation	250	W
RΘJA	Thermal Resistance From Junction To Ambient	400	℃/W
TJ	Operation Junction Temperature Range	-40~+ 125	℃
TSTG	Storage Temperature Range	-55~+ 150	℃

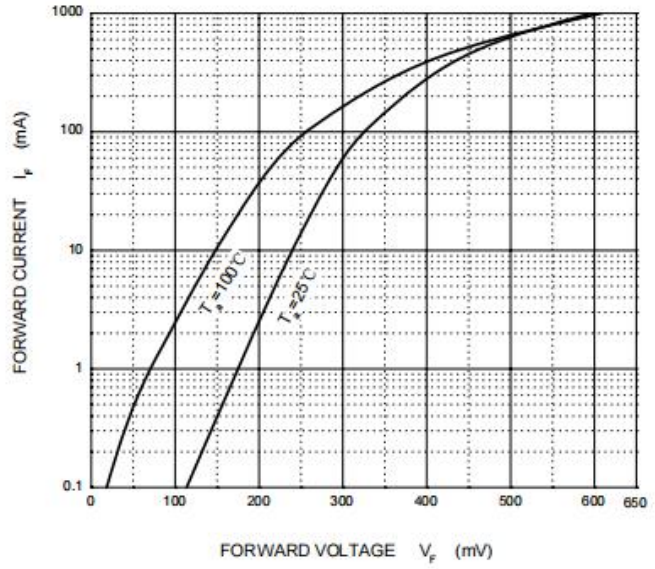
These ratings are limiting values above which the serviceability of the diode may be impaired.

ELECTRICAL CHARACTERISTICS (Ta=25℃)

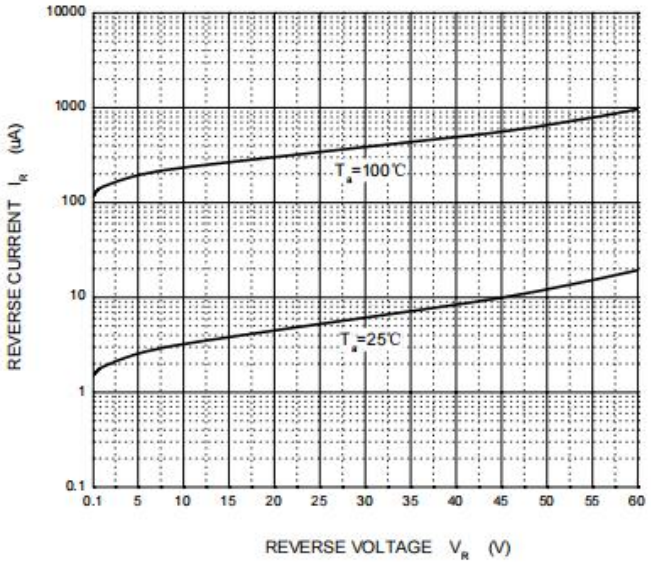
Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
VF	Forward voltage(1)	IF=1A			0.7	V
IR	Reverse voltage leakage current	VR=60V			0.1	A
Ctot	Total Capacitance	VR=4V, f=1.0MHz			120	F

ELECTRICAL CHARACTERISTICS CURVE

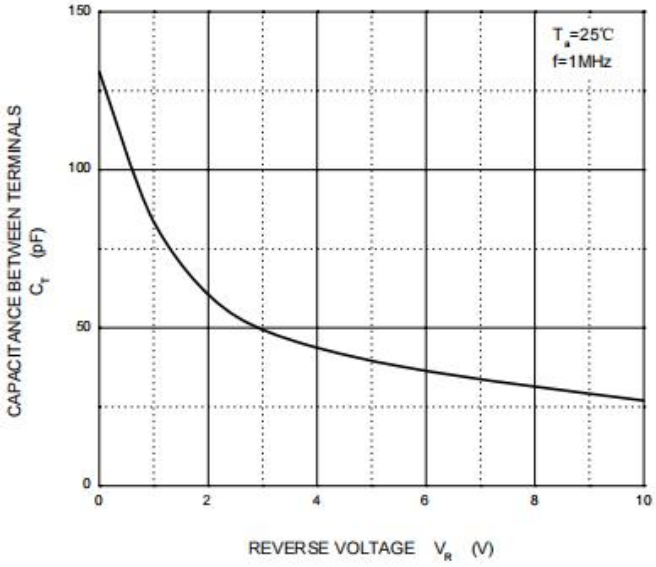
Forward Characteristics



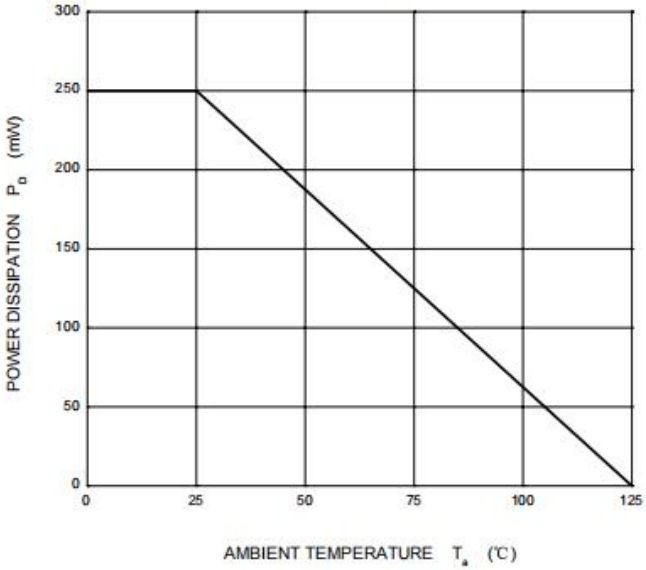
Reverse Characteristics



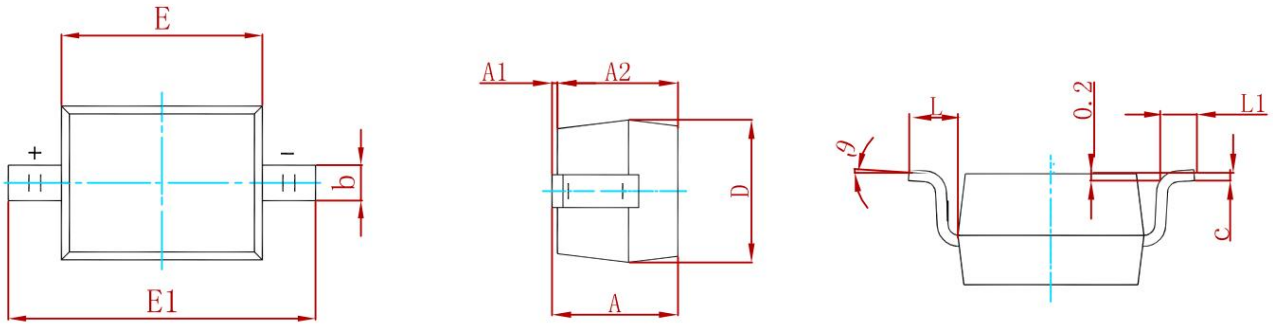
Capacitance Characteristics



Power Derating Curve

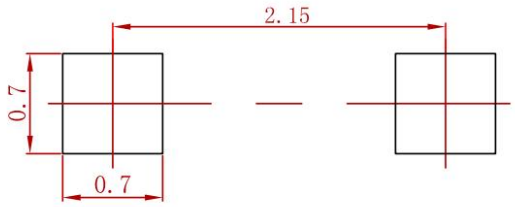


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1 .400	0.047	0.055
E	1.600	1 .800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
e	0°	8°	0。	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
B16WS	SOD-323	3000

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